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TABLE OF CONTENTS

Session 1A Moderator(s):	Sensing and Harvesting for Energy-Efficient System Design : Hidetoshi Onodera – Kyoto University	
1A.1	Online Fault Detection and Tolerance for Photovoltaic Energy Harvesting Systems	1
1A.2	Tunable Sensors for Process-Aware Voltage Scaling Tuck-Boon Chan, University of California at San Diego; Andrew B. Kahng, University of California at San Diego	?
1A.3	Collaborative Calibration of On-Chip Thermal Sensors using Performance Counters	15
Session 1B Moderator(s):	Test Cost and Security Prashant Goteti – Intel Corporation	
1B.1	Spatial Correlation Modeling for Probe Test Cost Reduction in RF Devices Nathan Kupp, Yale University; Ke Huang, University of Texas at Dallas; John M. Carulli Jr., Texas Instruments, Inc.; Yiorgos Makris, University of Texas at Dallas	23
1B.2	Small-Delay-Fault ATPG with Waveform Accuracy Matthias Sauer, University Freiburg; Alexander Czutro, University Freiburg; Ilia Polian, University of Passau; Bernd Becker, University Freiburg	30
1B.3	Experimental Analysis of a Ring Oscillator Network for Hardware Trojan Detection in a 90nm ASIC Andrew Ferraiuolo, University of Connecticut; Xuehui Zhang, University of Connecticut; Mohammad Tehranipoor, University of Connecticut	37
Session 1C Moderator(s):	DFM for EUV and Multiple Patterning Lithography Duo Ding – Oracle Corporation	
1C.1	Layout Small-Angle Rotation and Shift for EUV Defect Mitigation Hongbo Zhang, Synopsys, Inc.; Yuelin Du, University of Illinois at Urbana-Champaign; Martin D.F. Wong, University of Illinois at Urbana-Champaign; Yunfei Deng, GLOBALFOUNDRIES; Pawitter Mangat, GLOBALFOUNDRIES	43
1C.2	A Methodology for the Early Exploration of Design Rules for Multiple-Patterning Technologies Rani S. Ghaida, University of California, Los Angeles; Tanaya Sahu, University of California, Los Angeles; Parag Kulkarni, Qualcomm. Inc.: Puneet Gupta, University of California, Los Angeles	50

1C.3	A Polynomial Time Triple Patterning Algorithm for Cell based Row-Structure Layout	57
Session 1D	EMBEDDED TUTORIAL: Algorithms for Analysis and Optimization of Future Cyber Physical Systems	
Session 2A Moderator(s):	Hardware and Software Techniques for for Memory Hierarchy Optimization : Sri Parameswaran – University of New South Wales	
2A.1	Improving Last Level Cache Locality by Integrating Loop and Data Transformations	65
2A.2	Asymmetric DRAM Synthesis for Heterogeneous Chip Multiprocessors in 3D-Stacked Architecture	73
2A.3	Optimizing Bandwidth and Power of Graphics Memory with Hybrid Memory Technologies and Adaptive Data Migration Jishen Zhao, Pennsylvania State University; Yuan Xie, Pennsylvania State University, Advanced Micro Devices, Inc.	81
2A.4	Probabilistic Design Methodology to Improve Run-Time Stability and Performance of STT-RAM Caches Xiuyuan Bi, Polytechnic Institute of New York University; Zhenyu Sun, Polytechnic Institute of New York University; Hai Li, Polytechnic Institute of New York University; Wenqing Wu, Qualcomm, Inc.	88
Session 2B Moderator(s):	Simulation-Based Verification : Bryan Brady – IBM Corporation	
2B.1	Bridging Pre- and Post-Silicon Debugging with BiPeD Andrew DeOrio, University of Michigan; Jialin Li, University of Michigan; Valeria Bertacco, University of Michigan	95
2B.2	Novel Test Detection to Improve Simulation Efficiency – A Commercial Experiment	101
2B.3	A Robust General Constrained Random Pattern Generator for Constraints with Variable Ordering Bo-Han Wu, National Taiwan University; Chung-Yang (Ric) Huang, National Taiwan University	109
2B.4	Fast and Scalable Hybrid Functional Verification and Debug with Dynamically Reconfigurable Co-Simulation Somnath Banerjee, Mentor Graphics Pvt. Ltd., India; Tushar Gupta, Mentor Graphics Pvt. Ltd., India	115

	Advanced Topics in Routing : Aiqun Cao – Synopsys, Inc. Inki Hong – Cadence Design Systems, Inc.	
2C.1	TRIAD: A Triple Patterning Lithography Aware Detailed Router	123
2C.2	Maze Routing Algorithms with Exact Matching Constraints for Analog and Mixed Signal Designs Muhammet Mustafa Ozdal, Intel Corporation; Renato Fernandes Hentschke, Intel Corporation	130
2C.3	Reclaiming Over-the-IP-Block Routing Resources with Buffering-Aware Rectilinear Steiner Minimum Tree Construction Yilin Zhang, University of Texas at Austin; Ashutosh Chakraborty, Oracle Corporation; Salim Chowdhury, Oracle Corporation; David Z. Pan, University of Texas at Austin	137
2C.4	Construction of Rectilinear Steiner Minimum Trees with Slew Constraints over Obstacles Tao Huang, The Chinese University of Hong Kong; Evangeline F.Y. Young, The Chinese University of Hong Kong	144
Session 2D Moderator(s):	Computing in the Random Noise: The Bad, the Good, and the Amazing Grace Amit Singhee – IBM T.J. Watson Research Center	
2D.1	Noise based Logic: Why Noise? He Wen, Texas A&M University, Hunan University; Laszlo B. Kish, Texas A&M University	152
2D.2	An Efficient Implementation of Numerical Integration using Logical Computation on Stochastic Bit Streams Weikang Qian, Shanghai Jiao Tong University; Chen Wang, Shanghai Jiao Tong University; Peng Li, University of Minnesota; David J. Lilja, University of Minnesota; Kia Bazargan, University of Minnesota; Marc D. Riedel, University of Minnesota	156
2D.3	Utilizing Random Noise in Cryptography: Where is the Tofu? Hui Geng, Missouri University of Science and Technology; Jun Wu, Missouri University of Science and Technology; Jianming Liu, Missouri University of Science and Technology; Minsu Choi, Missouri University of Science and Technology; Yiyu Shi, Missouri University of Science and Technology	163
2D.4	Learning from Biological Neurons to Compute with Electronic Noise	168
Session 3A Moderator(s):	Timing and Behavioral Modeling Chenjie Gu – Intel Corporation Igor Keller – Cadence Design Systems, Inc.	
3A.1	On the Computation of Criticality in Statistical Timing Analysis S. Ramprasath, Indian Institute of Technology, Madras; V. Vasudevan, Indian Institute of Technology, Madras	172

3A.2	A Dynamic Method for Efficient Random Mismatch Characterization of Standard Cells	180
3A.3	Classifying Circuit Performance using Active-Learning Guided Support Vector Machines Honghuang Lin, Texas A&M University; Peng Li, Texas A&M University	187
Session 3B Moderator(s):	Formal Approaches to Verification Pankaj Chauhan – Calypto Design Systems, Inc.	
3B.1	Scalable Sampling Methodology for Logic Simulation: Reduced-Ordered Monte Carlo	195
3B.2	Trajectory-Directed Discrete State Space Modeling for Formal Verification of	
	Nonlinear Analog Circuits Sebastian Steinhorst, TUM CREATE Ltd.; Lars Hedrich, University of Frankfurt	202
3B.3	Word Level Feature Discovery to Enhance Quality of Assertion Mining	210
Session 3C Moderator(s):	Leakage and Technology-Aware Gate Sizing Cheng Zhuo – Intel Corporation Jianchao Lu – Synopsys, Inc.	
3C.1	Impact of Range and Precision in Technology on Cell-Based Design John Lee, University of California, Los Angeles; Puneet Gupta, University of California, Los Angeles	218
3C.2	An Efficient Algorithm for Library-Based Cell-Type Selection in	
	High-Performance Low-Power Designs Li Li, Northwestern University; Peng Kang, Northwestern University; Yinghai Lu, Synopsys, Inc.; Hai Zhou, Northwestern University	226
3C.3	Sensitivity-Guided Metaheuristics for Accurate Discrete Gate Sizing Jin Hu, University of Michigan; Andrew B. Kahng, University of California at San Diego; SeokHyeong Kang, University of California at San Diego; Myung-Chul Kim, University of Michigan; Igor L. Markov, University of Michigan	233
Session 3D <i>Moderator(s)</i> :	Dealing with Manufacturing and Reliability in Extremely Scaled CMOS and Beyond David Z. Pan – University of Texas at Austin Sachin Sapatnekar – University of Minnesota	
3D.1	Dealing with IC Manufacturability in Extreme Scaling	240
	Bei Yu, University of Texas at Austin; Jhih-Rong Gao, University of Texas at Austin; Duo Ding, University of Texas at Austin; Yongchan Ban, University of Texas at Austin; Jae-seok Yang, University of Texas at Austin; Kun Yuan, University of Texas at Austin; Minsik Cho, University of Texas at Austin; David Z. Pan, University of Texas at Austin	

3D.2	Circuit Reliability: From Physics to Architectures	243
	Jianxin Fang, University of Minnesota; Saket Gupta, University of Minnesota;	
	Sanjay V. Kumar, University of Minnesota; Sravan K. Marella, University of Minnesota;	
	Vivek Mishra, University of Minnesota; Pingqiang Zhou, University of Minnesota;	
	Sachin S. Sapatnekar, University of Minnesota	
Session 4A	System-Level Modeling and Optimization of Power Ground Networks	
	: Yiyu Shi – Missouri University of Science and Technology	
1120 1101 1101 (2)	Don MacMillen – Nimbic, Inc.	
4A.1	Stability Assurance and Design Optimization of Large Power Delivery Networks with	
771.1	Multiple On-Chip Voltage Regulators	247
	Suming Lai, Texas A&M University; Boyuan Yan, Texas A&M University;	2 . 7
	Peng Li, Texas A&M University	
4A.2	A Silicon-Validated Methodology for Power Delivery Modeling and Simulation	255
	Cheng Zhuo, Intel Corporation; Gustavo Wilke, Intel Corporation; Ritochit Chakraborty, Intel	200
	Corporation; Alaeddin Aydiner, Intel Corporation; Sourav Chakravarty, Intel Corporation;	
	Wei-Kai Shih, Intel Corporation	
4A.3	Optimization of On-Chip Switched-Capacitor DC-DC Converters for	
	High-Performance Applications	263
	Pingqiang Zhou, University of Minnesota; Won Ho Choi, University of Minnesota;	
	Bongjin Kim, University of Minnesota; Chris H. Kim, University of Minnesota;	
	Sachin S. Sapatnekar, University of Minnesota	
Session 4B	Challenges in 2D IC Technologies and Integration	
	Challenges in 3D IC Technologies and Integration : David Z. Pan – University of Texas at Austin	
, ,	· ·	
4B.1	Scaling the "Memory Wall"	271
	Shih-Lien Lu, Intel Corporation; Tanay Karnik, Intel Corporation; Ganapati Srinivasa, Intel	
	Corporation; Kai-Yuan Chao, Intel Corporation; Doug Carmean, Intel Corporation; Jim Held, Intel Corporation	
	Jim Heia, Intel Corporation	
4B.2	Test Challenges in Designing Complex 3D Chips: What is on the	
	Horizon for the EDA Industry?	273
	Sandeep Kumar Goel, Taiwan Semiconductor Manufacturing Co., Ltd.	
4B.3	3D Integrated Circuits: Designing in a New Dimension	274
	Robert Patti, Tezzaron Semiconductor	
Session 4C	Placement for the Next Decade	
	: Patrick Groeneveld – Synopsys, Inc.	
<i>Moaerator(s)</i>	: Fairick Groeneveia – Synopsys, Inc.	
4C.1	Progress and Challenges in VLSI Placement Research	275
	Igor L. Markov, University of Michigan; Jin Hu, University of Michigan;	
	Myung-Chul Kim, University of Michigan	
4C.2	The Upcoming Golden Age of Placement Research	n/a
	Shankar Krishnamoorthy, Mentor Graphics Corporation	

4C.3	Placement: Hot or Not?	283
	Charles Alpert, IBM Corporation; Zhuo Li, IBM Corporation; Gi-Joon Nam, IBM Corporation; C.N. Sze, IBM Corporation; Natarajan Viswanathan, IBM Corporation; Samuel I. Ward, IBM Corporation	
Session 4D Moderator(s).	Automation of Biological System Modeling and Analysis Subarna Sinha – Stanford University	
4D.1	Modeling and Design Automation of Biological Circuits and Systems Natasa Miskov-Zivanov, University of Pittsburgh; James R. Faeder, University of Pittsburgh; Chris J. Myers, University of Utah; Herbert M. Sauro, University of Washington	291
Session 5A Moderator(s)	Power-Aware Architecture and System Design : Youngsoo Shin – KAIST	
5A.1	CACTI-IO: CACTI with Off-Chip Power-Area-Timing Models	294
	Norman P. Jouppi, Hewlett-Packard Co.; Andrew B. Kahng, University of California at San Diego; Naveen Muralimanohar, Hewlett-Packard Co.; Vaishnav Srinivas, University of California at San Diego	
5A.2	AFReP: Application-Guided Function-Level Registerfile Power-Gating for	202
	Embedded Processors Hamed Tabkhi, Northeastern University; Gunar Schirner, Northeastern University	302
5A.3	Efficient Multiple-Bit Retention Register Assignment for Power Gated Design: Concept and Algorithms	309
	Yu-Guang Chen, National Tsing-Hua University; Yiyu Shi, Missouri University of Science and Technology; Kuan-Yu Lai, National Tsing-Hua University; Geng Hui, Missouri University of Science and Technology; Shih-Chieh Chang, National Tsing-Hua University	
Session 5B	Reliability and Thermal Issues in 3-D ICs	
Moderator(s).	: Miroslav Velev – Aries Design Automation, LLC	
5B.1	A Holistic Analysis of Circuit Timing Variations in 3D-ICs with Thermal and	217
	TSV-Induced Stress Considerations Sravan K. Marella, University of Minnesota; Sanjay V. Kumar, University of Minnesota; Sachin S. Sapatnekar, University of Minnesota	31/
5B.2	Electromigration-Aware Routing for 3-D ICs with Stress-Aware EM Modeling	325
5B.3	3D Transient Thermal Solver using Non-Conformal Domain Decomposition Approach	333

Session 5C	CAD Contests	
Moderator(s):	Zhuo Li – IBM Research, Austin	
	Iris Hui-Ru Jiang – National Chiao Tung University	
5C.1	Opening: Introduction to CAD Contest at ICCAD 2012	341
	Iris Hui-Ru Jiang, National Chiao Tung University; Zhuo Li, IBM Corporation;	
	Yih-Lang Li, National Chiao Tung University	
5C.2	ICCAD-2012 CAD Contest in Finding the Minimal Logic Difference for	
	Functional ECO and Benchmark Suite	342
	WoeiTzy Jong, Cadence Taiwan, Inc.; Hwei-Tseng Wang, Cadence Taiwan, Inc.;	
	Chengta Hsieh, Cadence Design Systems, Inc.; Kei-Yong Khoo, Cadence Design Systems, Inc.	
5C.3	ICCAD-2012 CAD Contest in Design Hierarchy Aware Routability-Driven	
	Placement and Benchmark Suite	345
	Natarajan Viswanathan, IBM Corporation; Charles Alpert, IBM Corporation; Cliff Sze, IBM Corporation; Zhuo Li, IBM Corporation; Yaoguang Wei, IBM Corporation	
5C.4	ICCAD-2012 CAD Contest in Fuzzy Pattern Matching for	
	Physical Verification and Benchmark Suite	349
	J. Andres Torres, Mentor Graphics Corporation	
Session 5D Moderator(s):	Power Characterization and Optimization in Smartphones Massoud Pedram – University of Southern California	
5D.1	System Energy Consumption is a Multi-Player Game	351
	Mian Dong, Rice University; Tian Lan, George Washington University; Lin Zhong, Rice University	
5D.2	Power Estimation and Modeling Challenges for Mobile Devices	n/a
5D.3	Thermal Management on Smart-Phones: A Case Study	n/a
	Ajat Hukkoo, Broadcom Corporation; Hwisung Jung, Broadcom Corporation; John Redmond, Broadcom Corporation	
Session 6A	Computational Approaches for Biological Systems	
Moderator(s):	Phillip Brisk – University of California, Riverside	
	Saurabh Srivastava – University of California, Berkeley	
6A.1	Voltage-Aware Chip-Level Design for Reliability-Driven Pin-Constrained EWOD Chips	353
	Sheng-Han Yeh, National Cheng Kung University; Jia-Wen Chang, National Cheng Kung	
	University; Tsung-Wei Huang, National Cheng Kung University; Tsung-Yi Ho, National Cheng Kung University	
6A.2	Compiling Program Control Flows into Biochemical Reactions	361
	De-An Huang, National Taiwan University; Jie-Hong R. Jiang, National Taiwan University;	201
	Ruei-Yang Huang, National Taiwan University; Chi-Yun Cheng, National Taiwan University	
6A.3	Dictionary-Based Error Recovery in Cyberphysical Digital-Microfluidic Biochips	369
	Yan Luo, Duke University; Krishnendu Chakrabarty, Duke University;	
	Tsung-Yi Ho, National Cheng Kung University	

6A.4	Reactant Minimization during Sample Preparation on Digital Microfluidic Biochips using Skewed Mixing Trees Juinn-Dar Huang, National Chiao Tung University; Chia-Hung Liu, National Chiao Tung University; Ting-Wei Chiang, National Chiao Tung University	377
Session 6B Moderator(s):	Fast Parallel Power Ground Network Simulation Methods Wil Schilders – Technische University Eindhoven Amitava Bhaduri – Intel Corporation	
6B.1	Fast Transform-Based Preconditioners for Large-Scale Power Grid Analysis on Massively Parallel Architectures Konstantis Daloukas, University of Thessaly; Nestor Evmorfopoulos, University of Thessaly; George Drasidis, University of Thessaly; Michalis Tsiampas, University of Thessaly; Panagiota Tsompanopoulou, University of Thessaly; George I. Stamoulis, University of Thessaly	384
6B.2	Deterministic Random Walk Preconditioning for Power Grid Analysis Jia Wang, Illinois Institute of Technology	392
6B.3	Efficient Parallel Power Grid Analysis via Additive Schwarz Method Ting Yu, University of Illinois at Urbana-Champaign; Zigang Xiao, University of Illinois at Urbana-Champaign; Martin D.F. Wong, University of Illinois at Urbana-Champaign	399
6B.4	Circuit Simulation via Matrix Exponential Method for Stiffness Handling and Parallel Processing Shih-Hung Weng, University of California at San Diego; Quan Chen, University of Hong Kong; Ngai Wong, University of Hong Kong; Chung-Kuan Cheng, University of California at San Diego	407
Session 6C Moderator(s):	Efficient Verification and Yield Estimation for Analog Circuits Ibrahim Elfadel – Masdar Institute of Science and Technology Eric Keiter – Sandia National Laboratories	
6C.1	An Efficient Control Variates Method for Yield Estimation of Analog Circuits based on a Local Model Pierre-Francois Desrumaux, Cambridge Silicon Radio; Yoan Dupret, Cambridge Silicon Radio; Jens Tingleff, Cambridge Silicon Radio; Sean Minehane, Cambridge Silicon Radio; Mark Redford, Cambridge Silicon Radio; Laurent Latorre, Laboratoire d'Informatique de Robotique et de Microélectronique de Montpellier; Pascal Nouet, Laboratoire d'Informatique de Robotique et de Microélectronique de Montpellier	415
6C.2	A Fast Time-Domain EM-TCAD Coupled Simulation Framework via Matrix Exponential Quan Chen, University of Hong Kong; Wim Schoenmaker, Magwel; Shih-Hung Weng, University of California at San Diego; Chung-Kuan Cheng, University of California at San Diego; Guan-Hua Chen, University of Hong Kong; Li-Jun Jiang, University of Hong Kong; Ngai Wong, University of Hong Kong	422
6C.3	GPSCP: A General-Purpose Support-Circuit Preconditioning Approach to Large-Scale SPICE-Accurate Nonlinear Circuit Simulations Xueqian Zhao, Michigan Technological University; Zhuo Feng, Michigan Technological University	429
6C.4	Verifying Dynamic Properties of Nonlinear Mixed-Signal Circuits via Efficient SMT-Based Techniques Leyi Yin, Texas A&M University; Yue Deng, Texas A&M University; Peng Li, Texas A&M University	436

Session 6D Moderator(s)	Toward Co-Design in High-Performance Computing Systems X. Sharon Hu – University of Notre Dame	
6D.1	Toward Codesign in High Performance Computing Systems Richard F. Barrett, Sandia National Laboratories; Sudip S. Dosanjh, Sandia National Laboratories; Michael A. Heroux, Sandia National Laboratories; X.S. Hu, University of Notre Dame; S. Parker, NVIDIA Corporation; J. Shalf, Lawrence Berkeley National Lab	443
Session 7A Moderator(s)	System-Level Modeling and Optimization Sri Parameswaran – University of New South Wales	
7A.1	Accurate On-Chip Router Area Modeling with Kriging Methodology	450
7A.2	Distributed Memory Interface Synthesis for Network-on-Chips with 3D-Stacked DRAMs Yi-Jung Chen, National Chi Nan University; Chia-Lin Yang, National Taiwan University; Jian-Jia Chen, Karlsruhe Institute of Technology	458
7A.3	Efficient Design Space Exploration for Component-Based System Design	466
Session 7B Moderator(s)	High-Level Design Methods Mohammad A. Al Faruque – University of California, Irvine	
7B.1	Multiple Tunable Constant Multiplications: Algorithms and Applications	473
7B.2	The Synthesis of Complex Arithmetic Computation on Stochastic Bit Streams using Sequential Logic Peng Li, University of Minnesota; David J. Lilja, University of Minnesota; Weikang Qian, University of Michigan-Shanghai Jiao Tong University Joint Institute; Kia Bazargan, University of Minnesota; Marc Riedel, University of Minnesota	480
7B.3	Memory Partitioning and Scheduling Co-Optimization in Behavioral Synthesis Peng Li, Peking University; Yuxin Wang, Peking University; Peng Zhang, University of California, Los Angeles; Guojie Luo, Peking University; Tao Wang, Peking University; Jason Cong, University of California, Los Angeles	488
Session 7C Moderator(s)	The Next Wave: Top Challenges in Electromagnetic-Based Design Automation *Vikram Jandhyala – University of Washington	
7C.1	Confronting and Exploiting Operating Environment Uncertainty in Predictive Analysis of Signal Integrity Andreas C. Cangellaris, University of Illinois at Urbana-Champaign	496
7C.2	Multi-Scale, Multi-Physics Analysis for Device, Chip, Package, and Board Level	497
7C.3	Design Strategies for High-Dimensional Electromagnetic Systems	498

7C.4	Co-Simulations of Electromagnetic and Thermal Effects in Electronic Circuits using Non-Conformal Numerical Methods Jin-Fa Lee, Ohio State University; Yang Shao, Ohio State University; Zhen Peng, Ohio State University	499
Session 7D Moderator(s)	EMBEDDED TUTORIAL: Printable Electronics Mehdi Tahoori – Karlsruhe Institute of Technology	
Session 8A Moderator(s)	Runtime Adaptation for Performance and Reliability : Jian-Jia Chen – Karlsruhe Institute of Technology Naehyuck Chang – Seoul National University	
8A.1	ISBA: An Independent Set-Based Algorithm for Automated Partial Reconfiguration Module Generation Ruining He, Tsinghua University; Yuchun Ma, Tsinghua University; Kang Zhao, Tsinghua University; Jinian Bian, Tsinghua University	500
8A.2	Fine-Grained Hardware/Software Methodology for Process Migration in MPSoCs Tuo Li, University of New South Wales; Jude Angelo Ambrose, University of New South Wales; Sri Parameswaran, University of New South Wales	508
8A.3	Active Compensation Technique for the Thin-Film Transistor Variations and OLED Aging of Mobile Device Displays Xiang Chen, University of Pittsburgh; Beiye Liu, University of Pittsburgh; Yiran Chen, University of Pittsburgh; Mengying Zhao, City University of Hong Kong; Chun Jason Xue, City University of Hong Kong; Xiaojun Guo, Shanghai Jiao Tong University	516
Session 8B Moderator(s)	Challenges in Embedded CPU/GPU Core Design Sheng Li – Hewlett-Packard Labs.	
8B.1	Challenges in Validating Next-Generation GPU Compute Capable GPUs	n/a
8B.2	Implementing High-Performance, Low-Power Embedded Processors: Challenges and Solutions Koen Lampaert, Broadcom Corporation	523
8B.3	Latency Tolerance for Throughput Computing	524
Session 8C Moderator(s)	Emerging Technologies for More-Moore and More-than-Moore Eras Chun Jason Xue – City University of Hong Kong	
8C.1	Multi-Level Cell STT-RAM: Is it Realistic or Just a Dream? Yaojun Zhang, University of Pittsburgh; Lu Zhang, University of Pittsburgh; Wujie Wen, University of Pittsburgh; Guangyu Sun, Peking University; Yiran Chen, University of Pittsburgh	526
8C.2	Ultra-Low Power NEMS FPGA Sijing Han, Case Western Reserve University; Vijay Sirigiri, Case Western Reserve University; Daniel G. Saab, Case Western Reserve University; Massood Tabib-Azar, University of Utah	533

8C.3	Young-Joon Lee, Georgia Institute of Technology; Patrick Morrow, Intel Corporation; Sung Kyu Lim, Georgia Institute of Technology	. 539
Session 8D Moderator(s)	The Secret Art of Analog/Mixed-Signal Post-Silicon Validation : Eli Chiprout – Intel Corporation	
8D.1	Challenges in Post-Silicon Validation of High-Speed I/O Links	. 547
8D.2	Post-Silicon Modeling and Tuning of Analog/Mixed-Signal Circuits via Bayesian Model Fusion Xin Li, Carnegie Mellon University	. 551
8D.3	Validation Signature Testing: A Methodology for Post-Silicon Validation of Analog/Mixed-Signal Circuits A. Chatterjee, Georgia Institute of Technology; S. Deyati, Georgia Institute of Technology; B. Muldrey, Georgia Institute of Technology; S. Devarakond, Georgia Institute of Technology; A. Banerjee, Georgia Institute of Technology	. 553
Session 9A Moderator(s)	Novel Techniques for Network on Chips and Hardware Security: John Bainbridge – Sonics, Inc. Grant Martin – Tensilica, Inc.	
9A.1	Functional Post-Silicon Diagnosis and Debug for Networks-on-Chip	. 557
9A.2	TRACKER: A Low Overhead Adaptive NoC Router with Load Balancing Selection Strategy John Jose, Indian Institute of Technology, Madras; K.V. Mahathi, Indian Institute of Technology, Madras; J. Shiva Shankar, Indian Institute of Technology, Madras; Madhu Mutyam, Indian Institute of Technology, Madras	. 564
9A.3	Provably Complete Hardware Trojan Detection using Test Point Insertion Sheng Wei, University of California, Los Angeles; Kai Li, Rice University; Farinaz Koushanfar, Rice University; Miodrag Potkonjak, University of California, Los Angeles	. 569
9A.4	Using Standardized Quantization for Multi-Party PPUF Matching:	577
	Foundations and Applications Saro Meguerdichian, University of California, Los Angeles; Miodrag Potkonjak, University of California, Los Angeles	. 311
Session 9B Moderator(s)	Advances in Logic Synthesis : Iris Hui-Ru Jiang – National Chiao Tung University	
9B.1	Simultaneous Information Flow Security and Circuit Redundancy in Boolean Gates	. 585
9B.2	On Logic Synthesis for Timing Speculation Yuxi Liu, The Chinese University of Hong Kong; Rong Ye, The Chinese University of Hong Kong; Feng Yuan, The Chinese University of Hong Kong; Rakesh Kumar, University of Illinois at Urbana-Champaign; Qiang Xu, The Chinese University of Hong Kong	. 591

9B.3	Lazy Man's Logic Synthesis	597
	Wenlong Yang, Fudan University; Lingli Wang, Fudan University; Alan Mishchenko, University of California, Berkeley	
9B.4	Minimizing Area and Power of Sequential CMOS Circuits using Threshold Decomposition Niranjan Kulkarni, Arizona State University; Nishant Nukala, Arizona State University; Sarma Vrudhula, Arizona State University	605
Session 9C Moderator(s)	New Approaches in Physical Synthesis of Nano-Scale Analog Circuits: Sheldon Tan – University of California, Riverside	
9C.1	Performance-Driven Analog Placement Considering Monotonic Current Paths	613
9C.2	Configurable Analog Routing Methodology via Technology and Design Constraint Unification Po-Cheng Pan, National Chiao Tung University; Hung-Ming Chen, National Chiao Tung University; Yi-Kan Cheng, Taiwan Semiconductor Manufacturing Co., Ltd.; Jill Liu, Taiwan Semiconductor Manufacturing Co., Ltd.; Wei-Yi Hu, Taiwan Semiconductor Manufacturing Co., Ltd.	620
9C.3	Efficient Parametric Yield Estimation of Analog/Mixed-Signal Circuits via Bayesian Model Fusion Xin Li, Carnegie Mellon University; Wangyang Zhang, Carnegie Mellon University; Fa Wang, Carnegie Mellon University; Shupeng Sun, Carnegie Mellon University; Chenjie Gu, Intel Corporation	627
9C.4	Analytical-Based Approach for Capacitor Placement with Gradient Error Compensation and Device Correlation Enhancement in Analog Integrated Circuits	635
Session 9D Moderator(s)	Power Grid Simulation and Verification for Billion-Transistor VLSI Designs : Claude Moughanni – Lattice Semiconductor Corp.	
9D.1	2012 TAU Power Grid Simulation Contest: Benchmark Suite and Results	643
9D.2	PGT_SOLVER: An Efficient Solver for Power Grid Transient Analysis Ting Yu, University of Illinois at Urbana-Champaign; Martin D.F. Wong, University of Illinois at Urbana-Champaign	647
9D.3	PowerRush: Efficient Transient Simulation for Power Grid Analysis Jianlei Yang, Tsinghua University; Zuowei Li, Tsinghua University; Yici Cai, Tsinghua University; Qiang Zhuo, Tsinghua University	653
9D.4	Parallel Forward and Back Substitution for Efficient Power Grid Simulation	660
9D.5	Design Analysis of IC Power Delivery	664

9D.6	Power Grid Effects and Their Impact On-Die Eli Chiprout, Intel Corporation	. 667
9D.7	Overview of Vectorless/Early Power Grid Verification Farid N. Najm, University of Toronto	. 670
	Power-Efficient Design and Management of OLED Displays : Jason Xue – City University of Hong Kong	
10A.1	High-Performance Metal-Oxide TFT and its Application for High-Power Efficiency AMOLED Displays	n/a
	Gang Yu, CBRITE, Inc.; Chan-Long Shieh, CBRITE, Inc.	
10A.2	Transistor Technologies and Pixel Circuit Design for Efficient Active-Matrix Organic Light-Emitting Diode Displays	. 678
	Xiaojun Guo, Shanghai Jiao Tong University; Guangyu Yao, Shanghai Jiao Tong University; Xiaoli Xu, Shanghai Jiao Tong University; Wenjiang Liu, Shanghai Jiao Tong University; Tao Liu, Shanghai Jiao Tong University	
10A.3	Battery Cell Configuration for Organic Light Emitting Diode Display in Modern Smartphones and Tablets-PCs	679
	Donghwa Shin, Seoul National University; Kitae Kim, Seoul National University; Naehyuck Chang, Seoul National University; Massoud Pedram, University of Southern California	. 017
10A.4	Mobile Devices User – The Subscriber and also the Publisher of Real-Time OLED Display Power Management Plan	. 687
	Yiran Chen, University of Pittsburgh; Xiang Chen, University of Pittsburgh; Mengying Zhao, City University of Hong Kong; Chun Jason Xue, City University of Hong Kong	
	2-D and 3-D Physical Design Optimization Thorlindur Thorolfsson – North Carolina State University	
10B.1	Clock Mesh Synthesis with Gated Local Trees and Activity Driven Register Clustering	. 691
10B.2	Fast Approximation for Peak Power Driven Voltage Partitioning in Almost Linear Time Jia Wang, Michigan Technological University; Xiaodao Chen, Michigan Technological University; Lin Liu, Michigan Technological University; Shiyan Hu, Michigan Technological University	. 698
10B.3	Multiobjective Optimization of Deadspace, a Critical Resource for 3-D-IC Integration	. 705
10B.4	A Fast Maze-Free Routing Congestion Estimator with Hybrid Unilateral Monotonic Routing Wen-Hao Liu, National Chiao Tung University; Yih-Lang Li, National Chiao Tung University; Cheng-Kok Koh, Purdue University	. 713

Moderator(s): Sung Kyu Lim – Georgia Institute of Technology			
720			
ut;			
728			
736			
730			
742			

Session 10C Enabling Design for Resilience